

CONTACT

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EDUCATION

U OF CINCINNATI | DAAP

Industrial Design Class of 2019 (BS)

GPA: 3.833 Dean's List 2014 - 2019

AWARDS

Experienced-Based Learning Achievement Award - 2019

IDSA Central District SMA Winner - 2019

HAAS Cup Champion - 2014

SKILLS

DIGITAL

Photoshop, Illustrator, InDesign, Sketchbook Pro, SolidWorks, Keyshot, Premiere Pro, After Effects, HTML + CSS, Word, Excel, PowerPoint, Outlook

ANALOG

Foam modeling, pattern making, mold making, CNC machining, brainstorming, sketching, digital sketching, analog sketching, wood shop, metal shop

DESIGN EXPERIENCE

GARMIN

Industrial Design Intern Aug 2018 - Dec 2018

Support designer on one of the Garmin Edge products. Contributed from project kickoff through the rough model phase. Participated in rough sketch, refined sketch, and rough model phases and responsible for presenting the rough model review.

SAMSUNG

Industrial Design Intern Jan 2018 - May 2018

Responsible for a wide variety of design exploration and ideation through the use of sketching, Illustrator, CAD, and foam modeling. I was also the main designer on a project working with an engineer to package his idea into a functional prototype.

GARMIN

Industrial Design Intern May 2017 - Aug 2017

Designed a conceptual action camera for Garmin's Virb lineup. The design process included research, ideation sketching, illustrator ideation, concept sketching, 3D modeling, 3D printing and prototyping, and a presentation to Garmin management.

CATALYST PDG

Industrial Design Intern Aug 2016 - Dec 2016

One of three designers on a small product development team. Contributed to projects through sketching, Solidworks surface modeling, and rapid ideation. I also operated injection molding presses and helped out with various manufacturing efforts.

FARM DESIGN

Industrial Design Intern Jan 2016 - Apr 2016

Contributed to projects for several clients and was responsible for brainstorming, sketching (digital and analog), 3D modeling, keyshot rendering, UI storyboarding, and foam modeling for internal architectures and component layouts.